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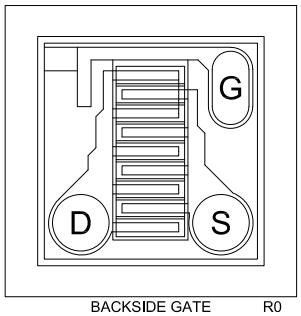
CP664V-2N5460
P-Channel JFET Die

The CP664V-2N5460 is a silicon P-Channel JFET designed for low level amplifier applications.



BACKSIDE GATE R0

MECHANICAL SPECIFICATIONS:

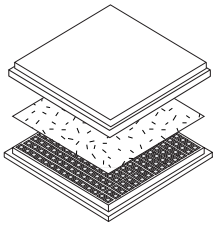
Die Size	19 x 19 MILS
Die Thickness	7.9 MILS
Drain Bonding Pad Size	4.2 MILS DIAMETER
Source Bonding Pad Size	4.2 MILS DIAMETER
Gate Bonding Pad Size	2.9 x 5.3 MILS
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au – 12,000Å
Scribe Alley Width	1.96 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	41,575

MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**		**UNITS**
Drain-Gate Voltage	V_{DG}	40	V
Reverse Gate-Source Voltage	V_{GSR}	40	V
Continuous Gate Current	I_G	10	mA
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	**TEST CONDITIONS**	**MIN**	**MAX**	**UNITS**
I_{GSS}	V_{GS}=20V, V_{DS}=0		5.0	nA
I_{DSS}	V_{DS}=15V, V_{GS}=0, f=1.0kHz	1.0	5.0	mA
BV_{GSS}	I_G=10μA	40		V
V_{GS}	V_{DS}=15V, I_D=0.1mA	0.5	4.0	V
$V_{GS(OFF)}$	V_{DS}=15V, I_D=1.0μA	0.75	6.0	V
$\|y_{fs}\|$	V_{DS}=15V, V_{GS}=0, f=1.0kHz	1.0K	4.0K	μS
$\|y_{os}\|$	V_{DS}=15V, V_{GS}=0, f=1.0kHz		75	μS
C_{rss}	V_{DS}=15V, V_{GS}=0, f=1.0MHz		2.0	pF
C_{iss}	V_{DS}=15V, V_{GS}=0, f=1.0MHz		7.0	pF
e_N	V_{DS}=15V, V_{GS}=0, f=100Hz, BW=1.0Hz		115	nV/$\sqrt{Hz}$
NF	V_{DS}=15V, V_{GS}=0, f=100Hz, R_G=1.0MΩ, BW=1.0Hz		2.5	dB

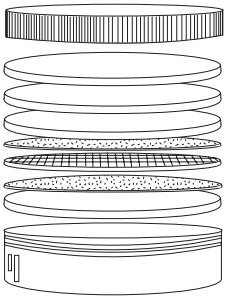
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

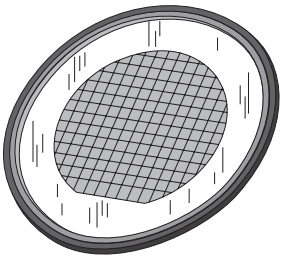
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



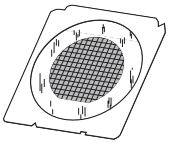
UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)



Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.

Visit the Central website for a complete listing of specifications:
www.centralsemi.com/bdspecs

R2 (3-April 2017)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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